

NCE N-Channel Enhancement Mode Power MOSFET

General Description

The NCE7560K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Features

- $V_{DS}=75V$; $I_D=60A@V_{GS}=10V$;
 $R_{DS(ON)}<8.5m\Omega @V_{GS}=10V$
- Special process technology for high ESD capability
- Special designed for Convertors and power controls
- High density cell design for ultra low R_{dson}
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

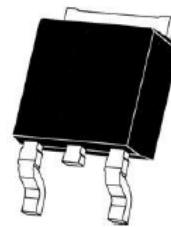
Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

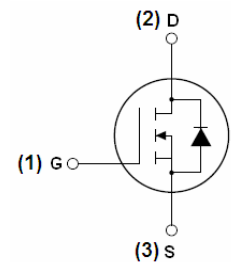
Product Summary

| | | |
|-------------------|------------|------------|
| BV_{DSS} typ. | 84 | V |
| $R_{DS(ON)}$ typ. | 6.8 | m Ω |
| | 8.5 | m Ω |
| I_D | 60 | A |

100% UIS TESTED!



TO-252-2L top view



Schematic diagram

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|----------|
| NCE7560K | NCE7560K | TO-252-2L | - | - | - |

Table 1. Absolute Maximum Ratings ($T_C=25^\circ C$)

| Parameter | Symbol | Value | Unit |
|---|-----------------|------------|---------------|
| Drain-Source Voltage ($V_{GS}=0V$) | V_{DS} | 75 | V |
| Gate-Source Voltage ($V_{DS}=0V$) | V_{GS} | ± 20 | V |
| Drain Current (DC) at $T_C=25^\circ C$ | $I_{D(DC)}$ | 60 | A |
| Drain Current (DC) at $T_C=100^\circ C$ | $I_{D(DC)}$ | 42 | A |
| Drain Current-Continuous@ Current-Pulsed (Note 1) | $I_{DM(pluse)}$ | 310 | A |
| Peak diode recovery voltage | dv/dt | 30 | V/ns |
| Maximum Power Dissipation($T_C=25^\circ C$) | P_D | 140 | W |
| Derating factor | | 0.95 | W/ $^\circ C$ |
| Single pulse avalanche energy (Note 2) | E_{AS} | 300 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | $^\circ C$ |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.EAS condition: $T_J=25^\circ C, V_{DD}=37.5V, V_G=10V, L=0.5mH$

Table 2. Thermal Characteristic

| Parameter | Symbol | Value | Unit |
|---|------------|-------|---------------|
| Thermal Resistance, Junction-to-Case (Maximum) | R_{thJC} | 1.05 | $^{\circ}C/W$ |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R_{thJA} | 50 | $^{\circ}C/W$ |

Table 3. Electrical Characteristics ($T_C=25^{\circ}C$ unless otherwise noted)

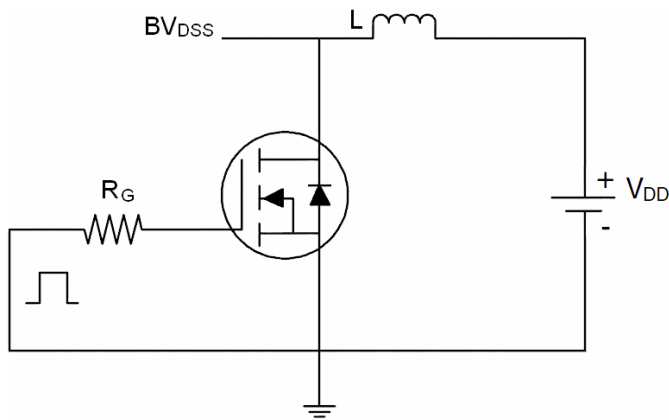
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|--------------|--|-----|------|-----------|------------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 75 | 84 | - | V |
| Zero Gate Voltage Drain Current($T_C=25^{\circ}C$) | I_{DSS} | $V_{DS}=75V, V_{GS}=0V$ | - | - | 1 | μA |
| Zero Gate Voltage Drain Current($T_C=125^{\circ}C$) | I_{DSS} | $V_{DS}=75V, V_{GS}=0V$ | - | - | 10 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2 | 3 | 4 | V |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=30A$ | - | 6.8 | 8.5 | m Ω |
| Dynamic Characteristics | | | | | | |
| Forward Transconductance | g_{FS} | $V_{DS}=5V, I_D=30A$ | | 66 | - | S |
| Input Capacitance | C_{iss} | $V_{DS}=25V, V_{GS}=0V,$ $F=1.0MHz$ | | 4400 | - | PF |
| Output Capacitance | C_{oss} | | | 340 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | | 260 | - | PF |
| Total Gate Charge | Q_g | $V_{DS}=30V, I_D=30A,$ $V_{GS}=10V$ | | 100 | - | nC |
| Gate-Source Charge | Q_{gs} | | | 20 | - | nC |
| Gate-Drain Charge | Q_{gd} | | | 30 | - | nC |
| Switching times | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=30V, I_D=2A, R_L=15\Omega$ $V_{GS}=10V, R_G=2.5\Omega$ | - | 17.8 | - | nS |
| Turn-on Rise Time | t_r | | - | 11.8 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 56 | - | nS |
| Turn-Off Fall Time | t_f | | - | 14.6 | - | nS |
| Source- Drain Diode Characteristics | | | | | | |
| Source-drain current(Body Diode) | I_{SD} | | - | - | 80 | A |
| Pulsed Source-drain current(Body Diode) | I_{SDM} | | - | - | 320 | A |
| Forward on voltage ^(Note 1) | V_{SD} | $T_j=25^{\circ}C, I_{SD}=30A, V_{GS}=0V$ | - | - | 1.2 | V |
| Reverse Recovery Time ^(Note 1) | t_{rr} | $T_j=25^{\circ}C, I_F=75A, di/dt=100A/\mu s$ | - | - | 36 | nS |
| Reverse Recovery Charge ^(Note 1) | Q_{rr} | | - | - | 56 | nC |
| Forward Turn-on Time | t_{on} | Intrinsic turn-on time is negligible(turn-on is dominated by L_S+L_D) | | | | |

Notes

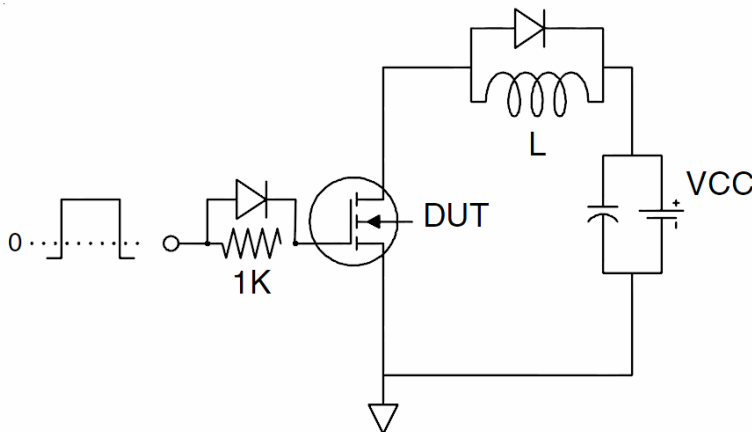
 1. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 1.5\%$, $R_G=25\Omega$, Starting $T_j=25^{\circ}C$

Test Circuit

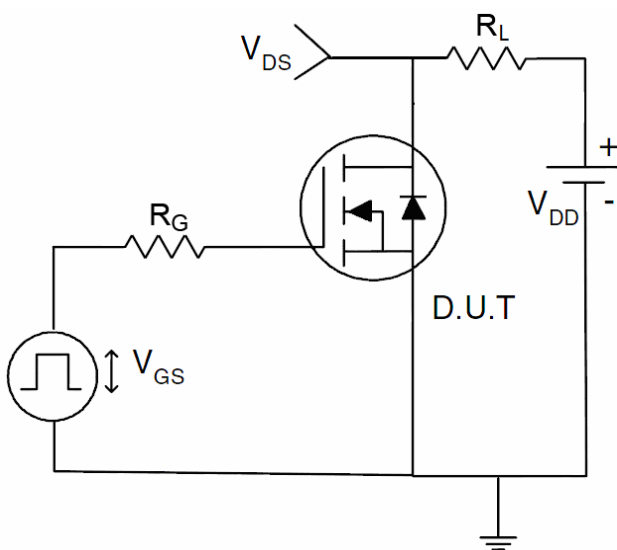
1) E_{AS} test circuit



2) Gate charge test circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (curves)

Figure1. Safe operating area

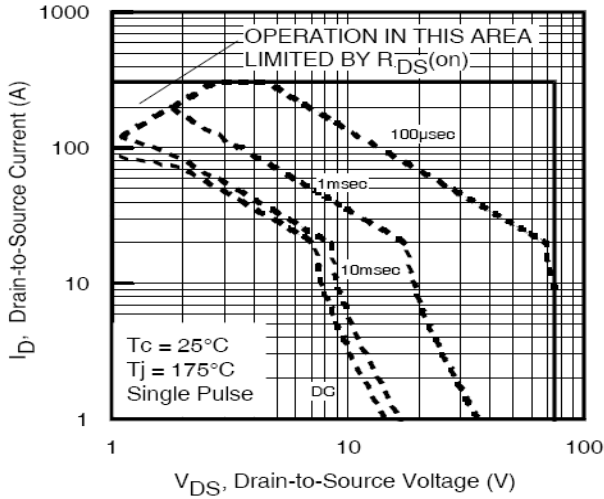


Figure2. Source-Drain Diode Forward Voltage

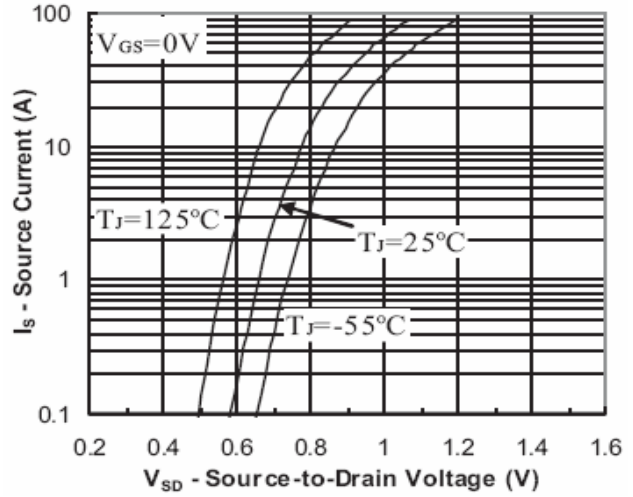


Figure3. Output characteristics

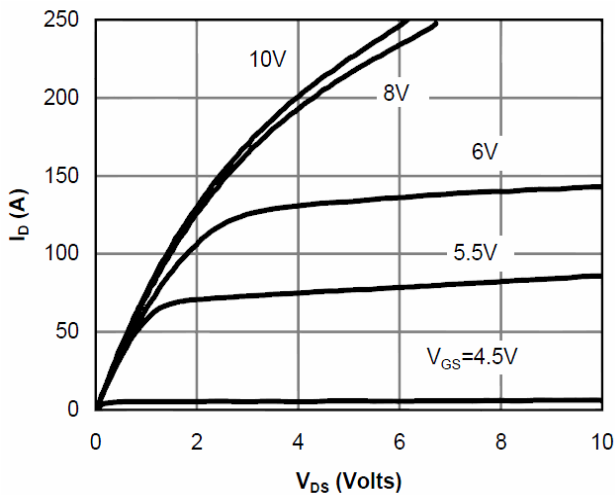


Figure4. Transfer characteristics

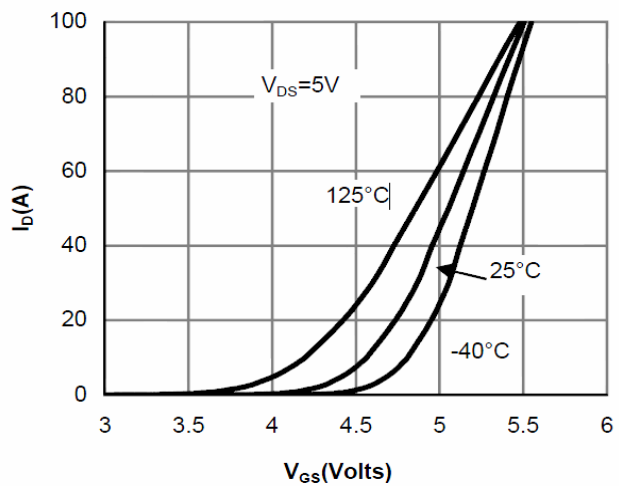


Figure5. Static drain-source on resistance

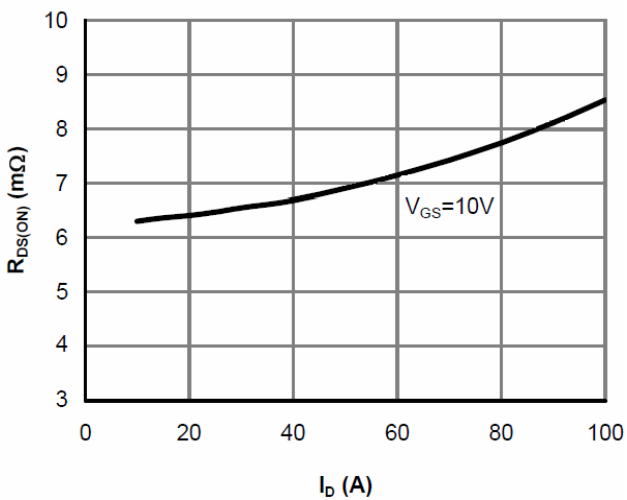


Figure6. $R_{DS(ON)}$ vs Junction Temperature

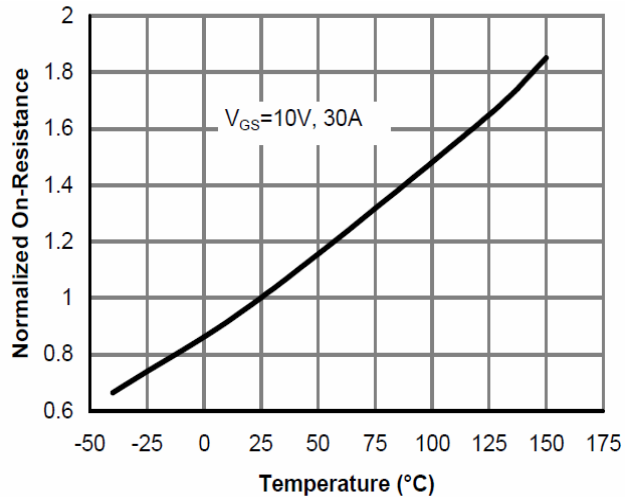


Figure7. BV_{DSS} vs Junction Temperature

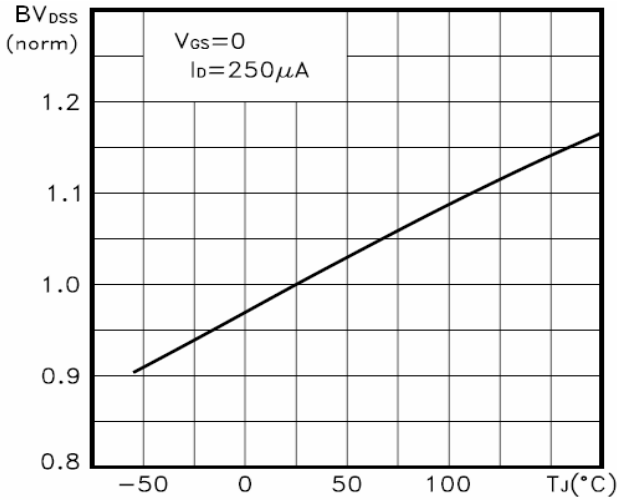


Figure8. $V_{GS(th)}$ vs Junction Temperature

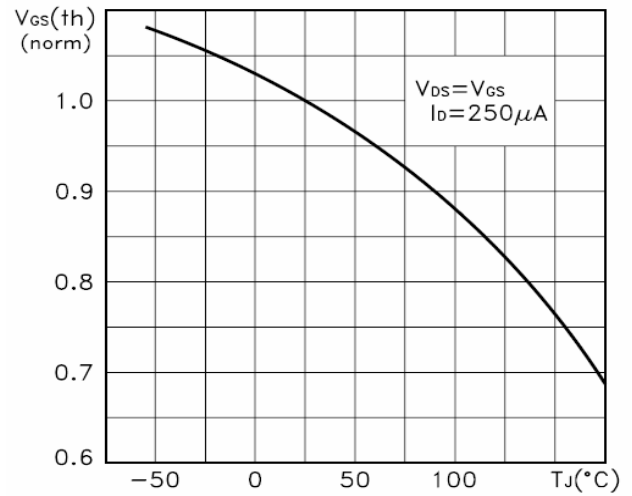


Figure9. Gate charge waveforms

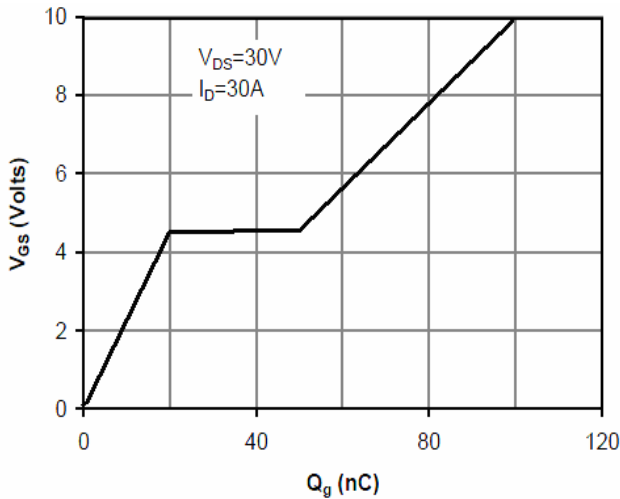


Figure10. Capacitance

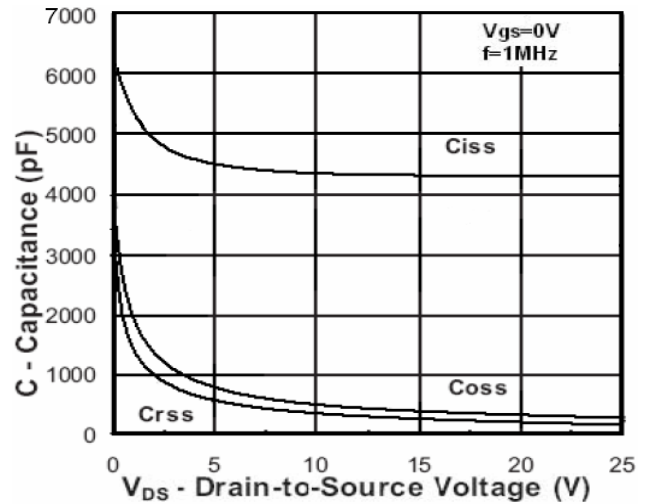
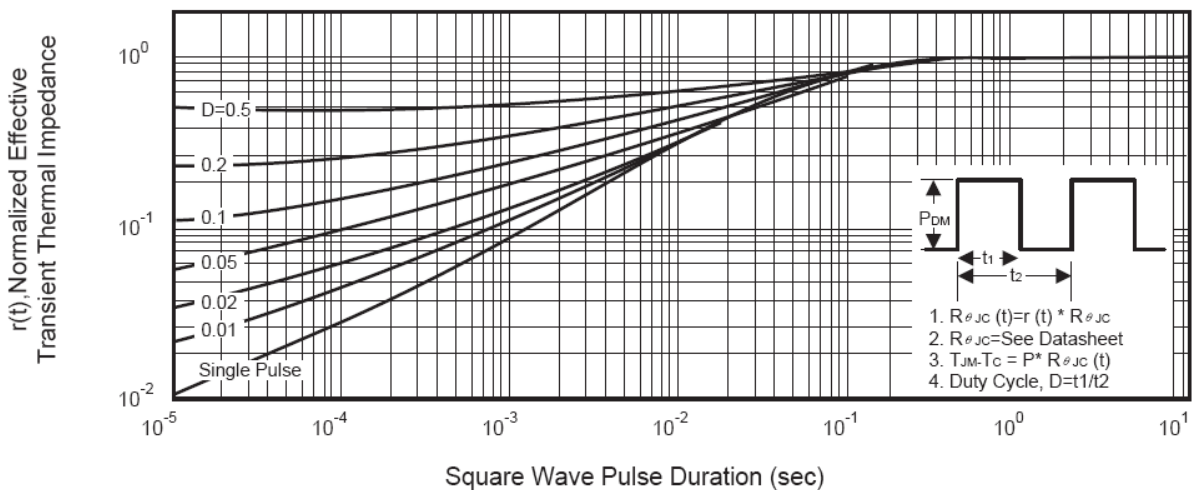
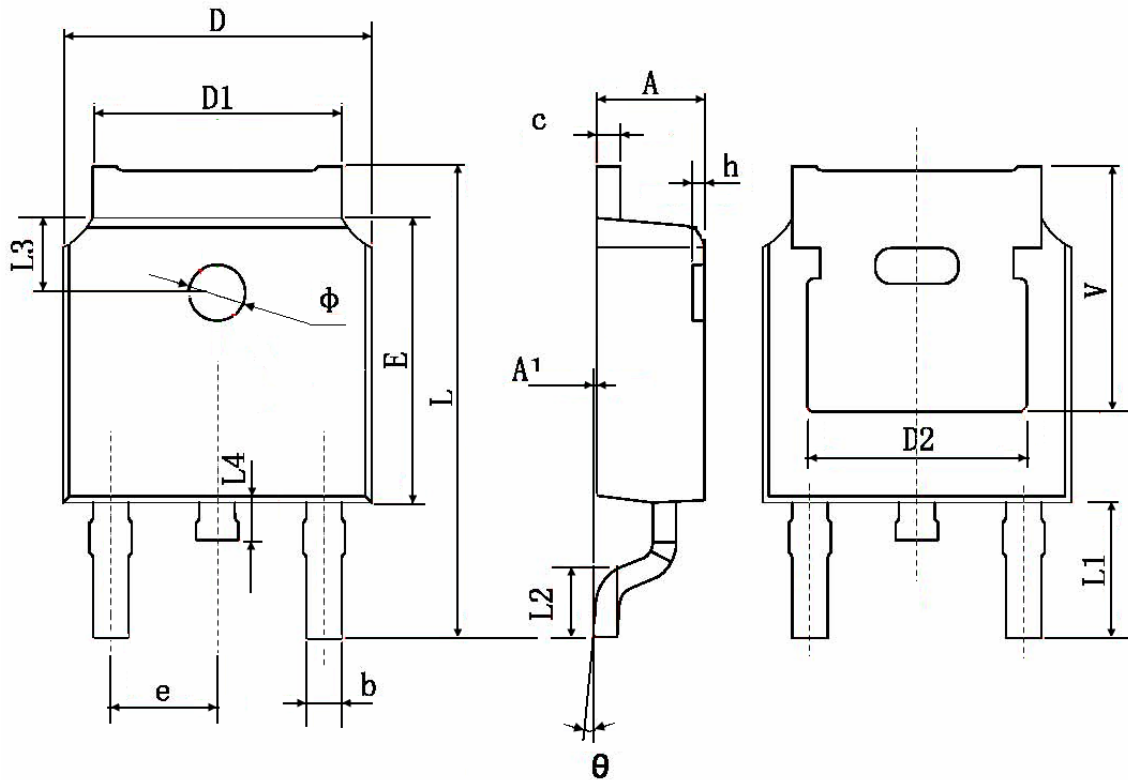


Figure11. Normalized Maximum Transient Thermal Impedance



TO-252 Package Information


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| b | 0.660 | 0.860 | 0.026 | 0.034 |
| c | 0.460 | 0.580 | 0.018 | 0.023 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| D2 | 4.830 TYP. | | 0.190 TYP. | |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| e | 2.186 | 2.386 | 0.086 | 0.094 |
| L | 9.800 | 10.400 | 0.386 | 0.409 |
| L1 | 2.900 TYP. | | 0.114 TYP. | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 |
| L3 | 1.600 TYP. | | 0.063 TYP. | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 |
| φ | 1.100 | 1.300 | 0.043 | 0.051 |
| θ | 0° | 8° | 0° | 8° |
| h | 0.000 | 0.300 | 0.000 | 0.012 |
| V | 5.350 TYP. | | 0.211 TYP. | |

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